# MBR1035, MBR1045

# **SWITCHMODE™ Power Rectifiers**

#### **Features and Benefits**

- Low Forward Voltage
- Low Power Loss/High Efficiency
- High Surge Capacity
- 175°C Operating Junction Temperature
- 10 A Total
- Pb-Free Packages are Available\*

#### **Applications**

- Power Supply Output Rectification
- Power Management
- Instrumentation

#### **Mechanical Characteristics**

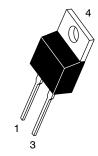
- Case: Epoxy, Molded
- Epoxy Meets UL 94, V-0 @ 0.125 in
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperatures for Soldering Purposes: 260°C Max. for 10 Seconds
- ESD Rating: Human Body Model 3B Machine Model C



#### ON Semiconductor®

# SCHOTTKY BARRIER RECTIFIERS 10 AMPERES 35 to 45 VOLTS





#### MARKING DIAGRAM



A = Assembly Location

TO-220AC

CASE 221B

**PLASTIC** 

Y = Year
WW = Work Week
G = Pb-Free Package
B10x5 = Device Code
x = 3 or 4
KA = Diode Polarity

#### **ORDERING INFORMATION**

Device	Package	Shipping
MBR1035	TO-220	50 Units/Rail
MBR1035G	TO-220 (Pb-Free)	50 Units/Rail
MBR1045	TO-220	50 Units/Rail
MBR1045G	TO-220 (Pb-Free)	50 Units/Rail

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage MBR1035	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	35	V
MBR1045	VH.	45	
Average Rectified Forward Current (T <sub>C</sub> = 135°C, Per Device)	I <sub>F(AV)</sub>	10	Α
Peak Repetitive Forward Current, (Square Wave, 20 kHz, T <sub>C</sub> = 135°C)	I <sub>FRM</sub>	10	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	IFSM	150	Α
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)		1.0	Α
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature (Note 1)	TJ	-65 to +175	°C
Voltage Rate of Change (Rated V <sub>R</sub> )	dv/dt	10,000	V/μs

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

#### THERMAL CHARACTERISTICS

Characteristic	Conditions	Symbol	Max	Unit
Maximum Thermal Resistance, Junction-to-Case	Min. Pad	$R_{ heta JC}$	2.0	°C/W
Maximum Thermal Resistance, Junction-to-Ambient	Min. Pad	$R_{\theta JA}$	60	

#### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Min	Typical	Max	Unit
Instantaneous Forward Voltage (Note 2)	VF	- - -	0.55 0.67 0.78	0.57 0.72 0.84	V
Instantaneous Reverse Current (Note 2) (Rated dc Voltage, Tj = 125°C) (Rated dc Voltage, Tj = 25°C)	i <sub>R</sub>		5.3 0.008	15 0.1	mA

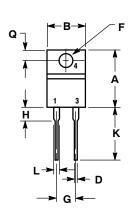
<sup>2.</sup> Pulse Test: Pulse Width = 300  $\mu s,$  Duty Cycle  $\leq$  2.0%.

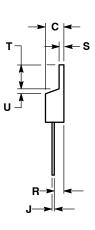
<sup>1.</sup> The heat generated must be less than the thermal conductivity from Junction–to–Ambient:  $dP_D/dT_J < 1/R_{\theta JA}$ .

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#### **PACKAGE DIMENSIONS**

TO-220 CASE 221B-04 ISSUE E





- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
A	0.595	0.620	15.11	15.75	
			_		
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.82	
D	0.025	0.035	0.64	0.89	
F	0.142	0.161	3.61	4.09	
G	0.190	0.210	4.83	5.33	
Н	0.110	0.130	2.79	3.30	
J	0.014	0.025	0.36	0.64	
K	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.14	1.52	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.14	1.39	
Т	0.235	0.255	5.97	6.48	
U	0.000	0.050	0.000	1 27	